



DMCB SERIES DIE

N-Channel Lateral DMOS FETs

The DMCB Series of single-pole, single-throw analog switches is designed for high speed switching in audio, video, and high-frequency applications. These devices are designed on the Siliconix DMOS process and utilize lateral construction to achieve low capacitance of ultra-fast switching speeds. The DMCB Series also features an integrated zener diode designed to protect the gate from electrical "Spikes" or overstress.

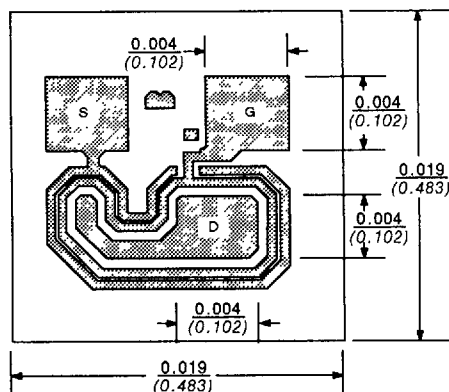
T-51-11

DMCB1CHP*	DMCB2CHP*
SD210DE SD214DE	SD211DE SD215DE SST211 SST215
*Meets or exceeds specification for all part numbers listed below	

For additional design information please consult the typical performance curves DMCA/B.

DESIGNED FOR:

- Ultra-High Speed Switching
- High Gain Amplifiers



Nominal Thickness
0.009 inches
0.228 mm

FEATURES

- < 1 ns Switching t_{ON}
- Ultra-Low Capacitance $C_G < 3.5$ pF
- g_{fs} (gain) > 10000 μ mhos

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS		UNITS
		DMCB1CHP	DMCB2CHP	
Gate-Source, Gate-Drain Voltage	V_{GS}, V_{GD}	± 40	-30/25	V
Gate-Substrate Voltage	V_{GB}	± 40	-0.3/25	
Drain-Source Voltage	V_{DS}	30		
Source-Drain Voltage	V_{SD}	10		
Drain-Substrate Voltage	V_{DB}	30		
Source-Substrate Voltage	V_{SB}	15		
Drain Current	I_D	50		mA
Storage Temperature	T_{stg}	-65 to 200		°C

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SPECIFICATIONS*				LIMITS					
PARAMETER	SYMBOL	TEST CONDITIONS	TYP ^b	DMCB1CHP		DMCB2CHP		UNIT	
				MIN	MAX	MIN	MAX		
STATIC									
Drain-Source Breakdown Voltage	V _{(BR)DS}	V _{GS} = V _{BS} = 0 V, I _D = 10 μA	35	30		30		V	
		V _{GS} = V _{BS} = -5 V, I _S = 10 nA	30	20		20			
Source-Drain Breakdown Voltage	V _{(BR)SD}	V _{GD} = V _{BD} = -5 V, I _S = 10 nA	22	20		20			
Drain-Substrate Breakdown Voltage	V _{(BR)DB}	V _{GB} = 0 V, I _D = 10 nA Source OPEN	35	25		25			
Source-Substrate Breakdown Voltage	V _{(BR)SB}	V _{GB} = 0 V, I _S = 10 μA Drain OPEN	35	25		25			
Drain-Source Leakage	I _{DS(OFF)}	V _{GS} = V _{BS} = -5 V	V _{DS} = 10 V	0.4				nA	
			V _{DS} = 20 V	0.9					
Source-Drain Leakage	I _{SD(OFF)}	V _{GD} = V _{BD} = -5 V	V _{DS} = 10 V	0.5					
			V _{DS} = 20 V	1					
Gate Leakage	I _{GBS}	V _{DB} = V _{GS} = 0 V, V _{GB} = 30 V	10 ⁻⁵					μA	
Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} = V _{GS(th)} , I _S = 1 μA V _{SB} = 0 V	0.7	0.5	2	0.5	2	V	
Drain-Source On-Resistance	r _{DS(ON)}	V _{SB} = 0 V, I _D = 1 mA	V _{GS} = 5 V	58				Ω	
			V _{GS} = 10 V	38					
			V _{GS} = 15 V	30					
			V _{GS} = 20 V	26					
			V _{GS} = 25 V	24					
DYNAMIC									
Forward Transconductance	g _{fs}	V _{DS} = 10 V, V _{SB} = 0 V I _D = 20 mA, f = 1 kHz	11					mS	
Output Conductance	g _{os}		0.9						
Gate-Node Capacitance	C _(GS+GD+GB)	V _{DS} = 10 V, f = 1 MHz V _{GS} = V _{BS} = -15 V	2.5					pF	
Drain-Node Capacitance	C _(GD+DB)		1.1						
Source-Node Capacitance	C _(GS+SB)		3.7						
Reverse Transfer Capacitance	C _{rss}		0.2						
SWITCHING									
Turn-On Time	t _{d(ON)}	V _{DD} = 5 V, R _L = 680 Ω V _{IN} = 0 to 5 V	0.5					ns	
	t _r		0.8						
Turn-Off Time	t _{d(OFF)}		2						
	t _f		6						

NOTES:

a. $T_A = 25^\circ\text{C}$ unless otherwise noted.

b. For design aid only, not subject to production testing.